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(54) Title: SLURRIES AND METHODS FOR CHEMICAL-MECHANICAL PLANARIZATION OF COPPER

(57) Abstract: The claimed invention involves a novel aqueous slurry for chemical-mechanical planarization that is effective for polishing copper at high polish rates. The aqueous slurry according to the present invention comprises particles of MoO₂ or MoO₃ and an oxidizing agent. A method for polishing copper by chemical-mechanical planarization includes contacting copper with a polishing pad and an aqueous slurry comprising particles Of MoO₂ or MoO₃ and an oxidizing agent.

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